Vishay Siliconix

Si1079X

RoHS

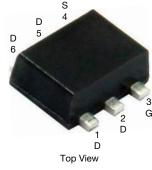
COMPLIANT HALOGEN

FREE

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PRODU	CT SUMMARY		
V _{DS} (V)	R _{DS(on)} (Ω) MAX.	I _D (A)	Q _g (TYP.)
	0.100 at V _{GS} = -4.5 V	-1.44	
-30	0.112 at V _{GS} = -3.7 V	-1.36	8.1 nC
	0.140 at V _{GS} = -2.5 V	-1.22	

SC-89 Single (6 leads)



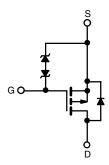
Marking Code: C Ordering Information: Si1079X-T1-GE3 (Lead (Pb)-free and Halogen-free)

FEATURES

- TrenchFET[®] power MOSFET
- Typical ESD performance 2500 V
- 100 % R_a tested
- Material categorization: For definitions of compliance please see <u>www.vishav.com/doc?99912</u>

APPLICATIONS

- Load switch for portable devices
- Power management



P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C, unless otherwise noted)						
PARAMETER		SYMBOL	LIMIT	UNIT		
Drain-Source Voltage		V _{DS}	-30	Ň		
Gate-Source Voltage		V _{GS}	± 12	V		
Continuous Drain Current (T. 150 °C)	T _A = 25 °C		-1.44 ^{b, c}			
Continuous Drain Current ($T_J = 150 \ ^\circ C$)	T _A = 70 °C	l _D	-1.15 ^{b, c}			
Pulsed Drain Current (t = 300 µs)		I _{DM}	-8	— A		
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	-0.28 ^{b, c}]		
Maximum Dawar Dissinction	T _A = 25 °C	D	0.33 ^{b, c}	W		
Maximum Power Dissipation	T _A = 70 °C	P _D	0.21 ^{b, c}	vv		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	-55 to 150	°C		

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT
Maximum Junction-to-Ambient ^{a, b}	t ≤ 5 s	Б	300	375	°C/W
Maximum Junction-to-Ambient	Steady State	R _{thJA}	360	450	C/ W

Notes

a. Maximum under steady state conditions is 450 °C/W.

b. Surface mounted on 1" x 1" FR4 board.

c. t = 5 s.

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PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static							
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = -250 μA	-30	-	-	V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	L 050 ··· A	-	-21	-	m\//º/	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = -250 μΑ	-	3	-	mV/°C	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = -250 \ \mu A$	-0.6	-	-1.5	V	
Cata Cauraa Laakaaa	1	$V_{DS} = 0 V, V_{GS} = \pm 12 V$	-	-	± 10		
Gate-Source Leakage	I _{GSS}	V_{DS} = 0 V, V_{GS} = ± 4.5 V	-	-	± 1		
Zave Cate Veltage Drain Coursent	1	$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}$	-	-	-1	μA	
Zero Gate Voltage Drain Current	IDSS	V_{DS} = -30 V, V_{GS} = 0 V, T_{J} = 85 °C	-	-	-10		
On-State Drain Current ^a	I _{D(on)}	V_{DS} = \geq -5 V, V_{GS} = -4.5 V	-8	-	-	A	
		$V_{GS} = -4.5 \text{ V}, \text{ I}_{D} = -1.4 \text{ A}$	-	0.083	0.100)	
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = -3.7 \text{ V}, \text{ I}_{D} = -1.3 \text{ A}$	-	0.093	0.112	Ω	
		$V_{GS} = -2.5 \text{ V}, \text{ I}_{D} = -0.7 \text{ A}$	-	0.108	0.140		
Forward Transconductance	g _{fs}	$V_{DS} = -15 \text{ V}, \text{ I}_{D} = -1.4 \text{ A}$	-	10	-	S	
Dynamic ^b							
Input Capacitance	C _{iss}		-	750	-	pF	
Output Capacitance	C _{oss}	V_{DS} = -15 V, V_{GS} = 0 V, f = 1 MHz	-	67	-		
Reverse Transfer Capacitance	C _{rss}		-	60	-		
Tatal Oata Obarra	0	V_{DS} = -15 V, V_{GS} = -10 V, I_D = -1.4 A	-	17	26		
Total Gate Charge	Qg		-	8.1	13	nC	
Gate-Source Charge	Q_gs	V_{DS} = -15 V, V_{GS} = -4.5 V, I_{D} = -1.4 A	-	1.2	-	no	
Gate-Drain Charge	Q_gd		-	2.2	-		
Gate Resistance	Rg	f = 1 MHz	3.6	18	36	Ω	
Turn-On Delay Time	t _{d(on)}		-	22	33		
Rise Time	t _r	V_{DD} = -15 V, R_L = 13 Ω	-	33	50		
Turn-Off Delay Time	t _{d(off)}	$\text{I}_\text{D}\cong$ -1.15 A, V_GEN = -4.5 V, R_g = 1 Ω	-	58	87		
Fall Time	t _f		-	30	45	ns	
Turn-On Delay Time	t _{d(on)}		-	5	10	115	
Rise Time	t _r	V_{DD} = -15 V, R_L = 13 Ω	-	20	30	-	
Turn-Off Delay Time	t _{d(off)}	$I_D\cong$ -1.15 A, V_{GEN} = -10 V, R_g = 1 Ω	-	80	120		
Fall Time	t _f		-	30	45		
Drain-Source Body Diode Characteri	stics						
Pulse Diode Forward Current ^a	I _{SM}		-	-	-8	Α	
Body Diode Voltage	V _{SD}	I _S = -1.15 A	-	-0.75	-1.2	V	
Body Diode Reverse Recovery Time	t _{rr}		-	16	24	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	$I_{}$ 1 15 A dl/dt - 100 A/vc	-	7	14	nC	
Reverse Recovery Fall Time	t _a	l _F = -1.15 A, dl/dt = 100 A/μs	-	9	-		
Reverse Recovery Rise Time	t _b		-	7	7 - ^{ns}		

Notes

a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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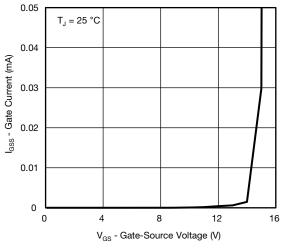
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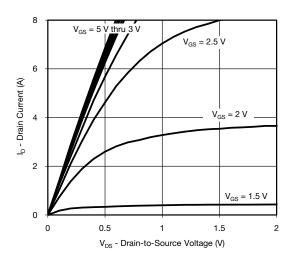


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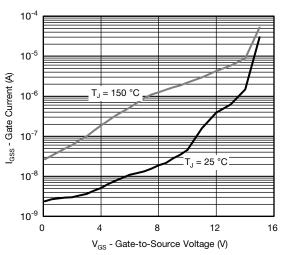
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



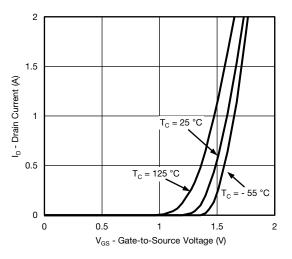
Gate Current vs. Gate-Source Voltage



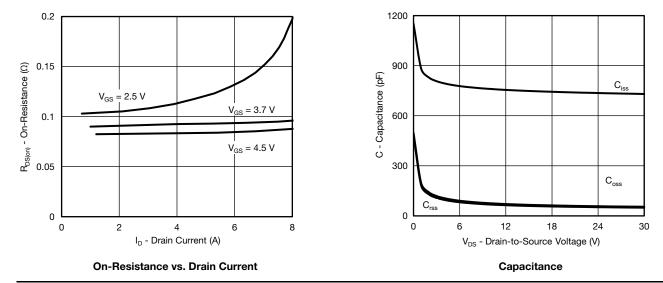
Output Characteristics



Gate Current vs. Gate-to-Source Voltage



Transfer Characteristics Curves vs. Temperature



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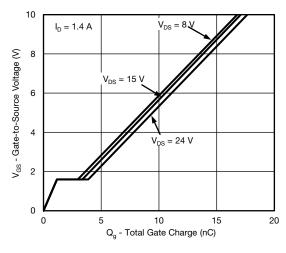
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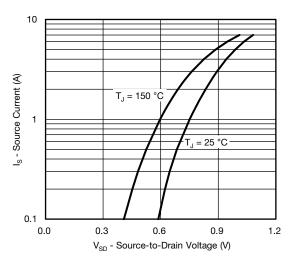


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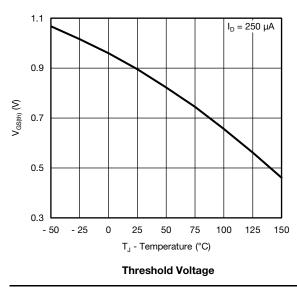
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)

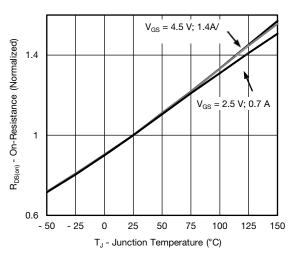


Gate Charge

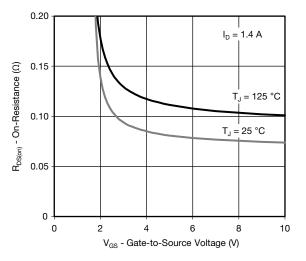


Source-Drain Diode Forward Voltage

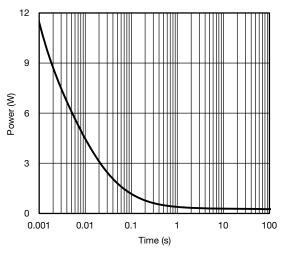




On-Resistance vs. Junction Temperature





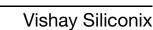


Single Pulse Power, Junction-to-Ambient

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4 ons. contact: proceeded Document Number: 62966

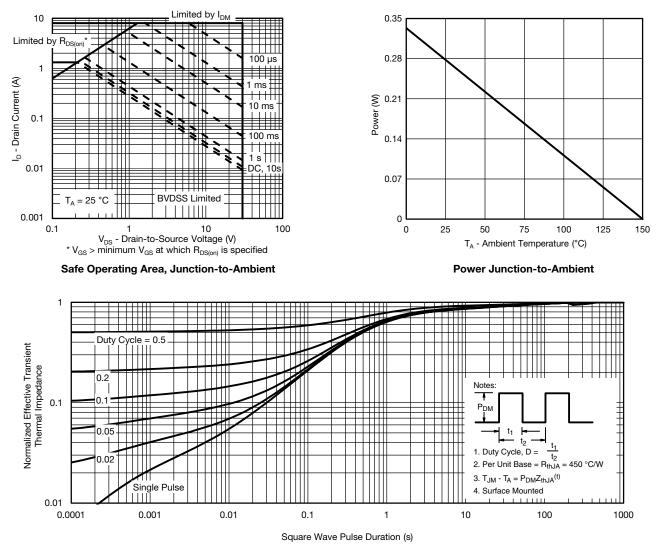
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TYPICAL CHARACTERISTICS ($T_A = 25 \text{ °C}$, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient

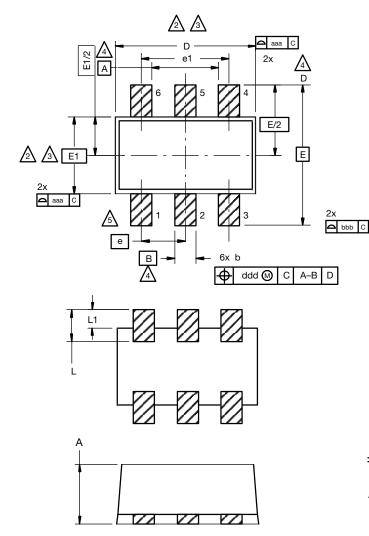
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SC-89 6-Leads (SOT-563F)



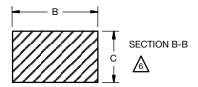
Notes

- 1. Dimensions in millimeters.
- Dimension D does not include mold flash, protrusions or gate burrs. Mold flush, protrusions or gate burrs shall not exceed 0.15 mm per dimension E1 does not include interlead flash or protrusion, interlead flash or protrusion shall not exceed 0.15 mm per side.
- Dimensions D and E1 are determined at the outmost extremes of the plastic body exclusive of mold flash, the bar burrs, gate burrs and interlead flash, but including any mismatch between the top and the bottom of the plastic body.

A Datums A, B and D to be determined 0.10 mm from the lead tip.

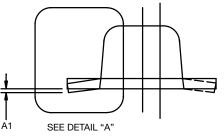
A Terminal numbers are shown for reference only.

These dimensions apply to the flat section of the lead between 0.08 mm and 0.15 mm from the lead tip.









DIM.	MILLIMETERS				
	MIN.	NOM.	MAX.		
А	0.56	0.58	0.60		
A1	0	0.02	0.10		
b	0.15	0.22	0.30		
С	0.10	0.14	0.18		
D	1.50	1.60	1.70		
E	1.50	1.60	1.70		
E1	1.15	1.20	1.25		
е	0.45	0.50	0.55		
e1	0.95	1.00	1.05		
L	0.25	0.35	0.50		
L1	0.10	0.20	0.30		
C14-0439-Rev DWG: 5880	v. C, 11-Aug-14				

Revision: 11-Aug-14

1 For technical questions, contact: <u>analogswitchtechsupport@vishay.com</u> Document Number: 71612

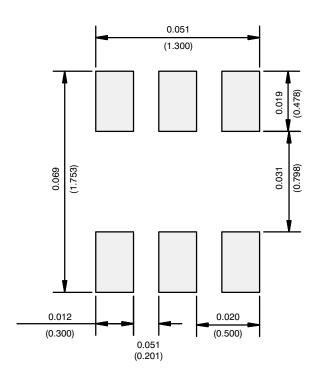
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Application Note 826

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RECOMMENDED MINIMUM PADS FOR SC-89: 6-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)

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